



SPACE
FOR BUSINESS
BUSINESS
FOR SPACE



TECHNOLOGY DESCRIPTION

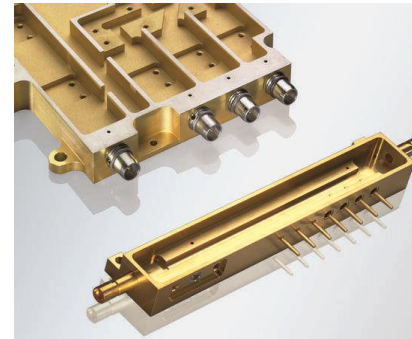
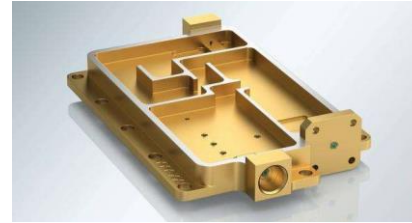
Hermetic microelectronic housings, which are often also referred to as hybrid housings, multichip module housings or IC housings, protect sensitive electrical assemblies and components under extremely harsh operating conditions. At the same time, they enable reliable power and signal transmission.

Hermetic housings fulfil the latest and most stringent specifications, including extreme performance and lifetime requirements where other components fail. The microelectronic housings offer reliability under high pressure, vibration and temperature conditions as well as optimal processability in production lines.



INNOVATIVE ASPECTS

- Maximum reliability – even in working environments with extreme pressure, vibrations and a max. temperature of 175°C.
- The microelectronic packaging offers exceptional thermal conductivity, making it ideal for managing heat in high performance applications.
- Glass-to-metal sealing enables the production of miniature 3D interconnecting solutions and paves the way for high-density input/output capabilities in hermetic, small-form-factor packages.



TECHNOLOGY READINESS (in space application)

TRL 9 (2024)

COUNTRY OF ORIGIN

Germany

LATEST UPDATE

06/2024

TAGS #housing #microelectronic #high pressure #high temperat. #hermetic #processability

APPLICATION AREAS

Aviation Construction & Civil Engineering Energy Electrical & Electronic Engineering Health Safety & Security Space technologies

TECH CARD

